



MakeMyPCB - Standard board build up 0-8 layers

0 Layer STD Build 1.60mm 0.062"

Core	1600µm	62mil
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1 Layer STD Build 1.60mm 0.062"

Core	1600µm	62mil
copper - 1	35µm	1oz

2 Layer STD Build 1.60mm 0.062"

copper - 1	18µm	1/2oz
Core	1600µm	62mil
copper - 2	18µm	1/2oz

4 Layer STD Build 1.60mm 0.062"

copper - 1	18µm	1/2oz
Prepreg 7628	200µm	8mil
Prepreg 7628	200µm	8mil
copper - 2	35µm	1oz
Core	710µm	27.95mil
copper - 3	35µm	1oz
Prepreg 7628	200µm	8mil
Prepreg 7628	200µm	8mil
copper - 4	18µm	1/2oz

6 Layer STD Build 1.60mm 0.062"

copper - 1	18µm	1/2oz
Prepreg 2125 or 2116	100µm	4mil
Prepreg 2125 or 2116	100µm	4mil
copper - 2	35µm	1oz
Core	360µm	14.2mil
copper - 3	35µm	1oz
Prepreg 2125 or 2116	100µm	4mil
Prepreg 2125 or 2116	100µm	4mil
copper - 4	35µm	1oz
Core	360µm	14.2mil
copper - 5	35µm	1oz
Prepreg 2125 or 2116	100µm	4mil
Prepreg 2125 or 2116	100µm	4mil
copper - 6	18µm	1/2oz

8 Layer STD Build 1.60mm 0.062"

copper - 1	18µm	1/2oz
Prepreg 2125 or 2116	100µm	4mil
Prepreg 2125 or 2116	100µm	4mil
copper - 2	35µm	1oz
Core	200µm	4mil
copper - 3	35µm	1oz
Prepreg 2125 or 2116	100µm	4mil
Prepreg 2125 or 2116	100µm	4mil
copper - 4	35µm	1oz
Core	200µm	4mil
copper - 5	35µm	1oz
Prepreg 2125 or 2116	100µm	4mil
Prepreg 2125 or 2116	100µm	4mil
copper - 6	35µm	1oz
Core	200µm	4mil
copper - 7	35µm	1oz
Prepreg 2125 or 2116	100µm	4mil
Prepreg 2125 or 2116	100µm	4mil
copper - 8	18µm	1/2oz

All materials are suitable for lead free soldering.
We exclusively use FR-4 improved materials

The minima for the key material parameters are: Td >= 325 °C
T260 >= 60 min
T288 >= 5 min
CTEz <= 3.7%
Tg >= 135°C

All used materials comply with the RoHS regulations